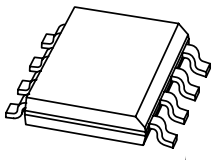
DATA SHEET



KMZ51
Magnetic field sensor

Product specification
Supersedes data 1998 Mar 24

2000 Jun 13

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Magnetic field sensor KMZ51

FEATURES

- High sensitivity
- Integrated compensation coil
- Integrated set/reset coil.

APPLICATIONS

- Navigation
- Current and earth magnetic field measurement
- Traffic detection.

DESCRIPTION

The KMZ51 is an extremely sensitive magnetic field sensor, employing the magnetoresistive effect of thin-film permalloy. The sensor contains one magnetoresistive Wheatstone bridge and integrated compensation and set/reset coils. The integrated compensation coil allows magnetic field measurement with current feedback loops to generate an output that is independent of drift in sensitivity. The orientation of sensitivity may be set or changed (flipped) by means of the integrated set/reset coil. A short current pulse should be applied to the compensation coil to recover (set) the sensor after exposure to strong disturbing magnetic fields. A negative current pulse will reset the sensor to reversed sensitivity. By use of periodically alternated flipping pulses and a lock-in amplifier, output is made independent of sensor and amplifier offset.

PINNING

PIN	SYMBOL	DESCRIPTION
1	$+I_{flip}$	flip coil
2	V_{CC}	bridge supply voltage
3	GND	ground
4	$+I_{comp}$	compensation coil
5	$-I_{comp}$	compensation coil
6	$-V_O$	bridge output voltage
7	$+V_O$	bridge output voltage
8	$-I_{flip}$	flip coil

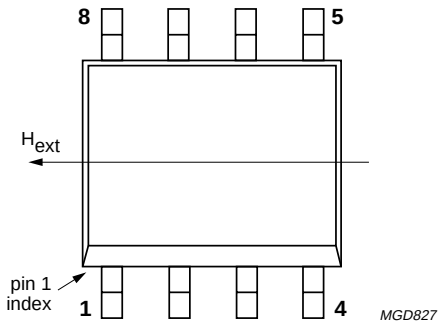


Fig.1 Simplified outline.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
V_{CC}	bridge supply voltage	–	5	8	V
S	sensitivity (uncompensated)	12	16	–	$\frac{mV/V}{kA/m}$
V_{offset}	offset voltage	–1.5	–	+1.5	mV/V
R_{bridge}	bridge resistance	1	–	3	kΩ
R_{comp}	compensation coil resistance	100	170	300	Ω
A_{comp}	compensation coil field factor; note 1	19	22	25	$\frac{A/m}{mA}$

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
R_{flip}	flip coil resistance	1	2	3	Ω
$I_{flip\ (min)}$	minimum recommended flipping current; note 2	800	1000	1200	mA
$t_{flip\ (min)}$	minimum flip pulse duration; note 2	1	3	100	μs

Notes

1. The compensation coil generates a field $H_{comp} = A_{comp} \times I_{comp}$ in addition to the external field H_{ext}. Sensor output will become zero if $H_{ext} = -H_{comp}$.
2. Average power consumption of the flipping coil, defined by current, pulse duration and pulse repetition rate may not exceed the specified limit, see Chapter “Limiting values”.

CIRCUIT DIAGRAM

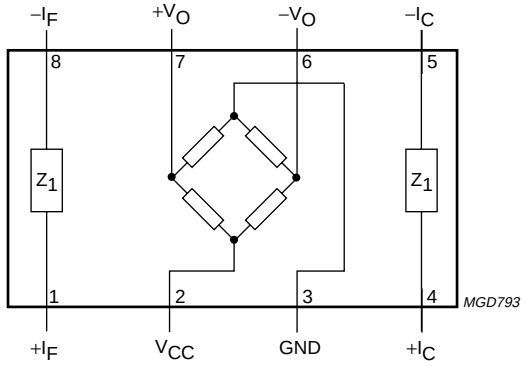


Fig.2 Simplified circuit diagram.

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
V_{CC}	bridge supply voltage	–	9	V
P_{tot}	total power dissipation	–	130	mW
T_{stg}	storage temperature	−65	+150	°C
T_{bridge}	bridge operating temperature	−40	+125	°C
I_{comp}	maximum compensation current	–	15	mA
$I_{flip\ (max)}$	maximum flipping current	–	1500	mA
$P_{flip\ (max)}$	maximum flipping power dissipation	–	50	mW
V_{isol}	voltage between isolated systems: flip coil and Wheatstone bridge; compensation coil and Wheatstone bridge; flip coil and compensation coil	–	60	V

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	VALUE	UNIT
$R_{th\ j\text{-}a}$	thermal resistance from junction to ambient	155	K/W

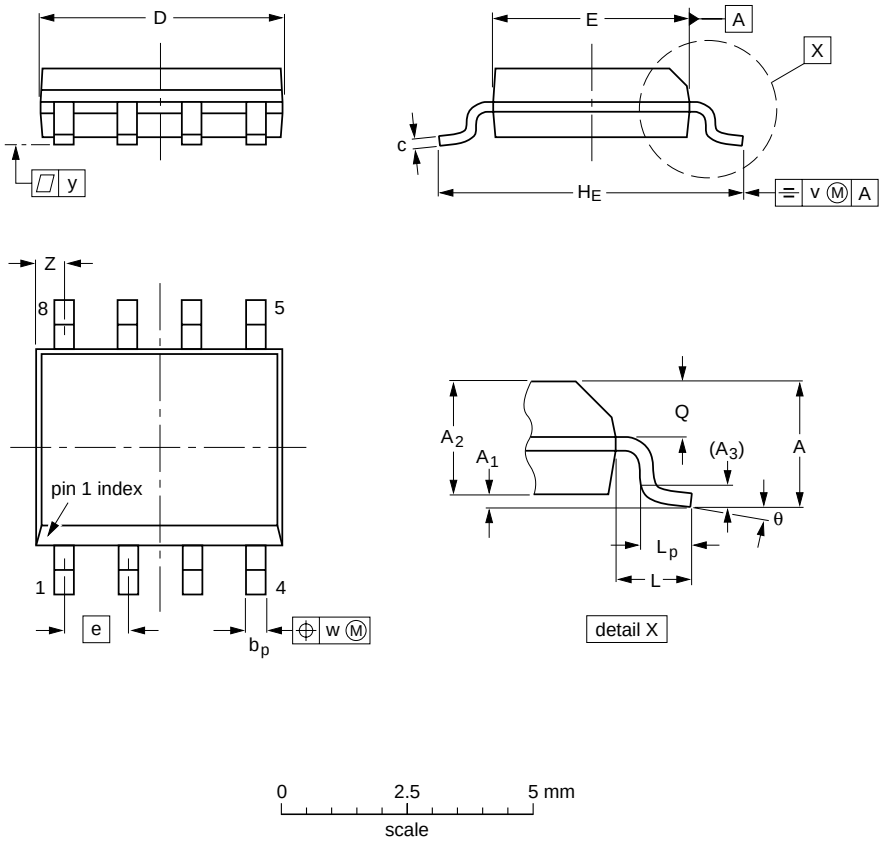
CHARACTERISTICS

T_{amb} = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_{CC}	bridge supply voltage		–	5	8	V
H_y	operating range in sensitive direction		–0.2	–	+0.2	kA/m
H_x	operating range perpendicular to sensitive direction		–0.2	–	+0.2	kA/m
S	sensitivity	open circuit	12	16	–	$\frac{mV/V}{kA/m}$
TCS	temperature coefficient of sensitivity	T_s = –25 to +125 °C	–	0.31	–	%/K
TCV_O	temperature coefficient of output voltage	V_{CC} = 5 V; T_{amb} = –25 to +125 °C	–	–0.4	–	%/K
		I_{CC} 3 mA; T_{amb} = –25 to +125 °C	–	–0.1	–	%/K
R_{bridge}	bridge resistance	resistance pins 2 to 3	1	–	3	kΩ
TCR_{bridge}	temperature coefficient of bridge resistance	T_{bridge} = –25 to +125 °C	–	0.3	–	%/K
V_{offset}	offset voltage		–1.5	0	+1.5	mV/V
TCV_{offset}	temperature coefficient of offset voltage	T_{bridge} = –25 to +125 °C	–3	0	+3	$\frac{\mu V/V}{K}$
FH	hysteresis of output voltage		–	–	2	%FS
R_{comp}	resistance of compensation coil	resistance pins 4 to 5	100	170	300	Ω
A_{comp}	field factor of compensation coil		19	22	25	$\frac{A/m}{mA}$
R_{flip}	resistance of set/reset conductor	resistance pins 1 to 8	1	2	3	Ω
TCR_{flip}	temperature coefficient of resistance of set/reset coil	T_{flip} = –25 to +125 °C	–	0.39	–	%/K
I_{flip}	recommended flipping current for stable operation		±800	±1000	±1200	mA
t_{flip}	flip pulse duration		1	3	100	µs
R_{isol}	isolating resistance	resistance pins 1 to 2, 1 to 4 and 2 to 4	1	–	–	mΩ
V_{isol}	voltage between isolated systems	voltage pins 1 to 2, 1 to 4 and 2 to 4	–	–	50	V
f	operating frequency		0	–	1	MHz

PACKAGE OUTLINE

SO8: plastic small outline package; 8 leads; body width 3.9 mm **SOT96-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D(1)	E(2)	e	H_E	L	L_p	Q	v	w	y	Z(1)	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	5.0 4.8	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8^o 0^o
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.20 0.19	0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT96-1	076E03	MS-012				~~97-05-22~~ 99-12-27

DATA SHEET STATUS

DATA SHEET STATUS	PRODUCT STATUS	DEFINITIONS (1)
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.
Product specification	Production	This data sheet contains final specifications. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.

Note

1. Please consult the most recently issued data sheet before initiating or completing a design.

DEFINITIONS

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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NOTES

Philips Semiconductors – a worldwide company

Argentina: see South America

Australia: 3 Figtree Drive, HOMEBUSH, NSW 2140,
Tel. +61 2 9704 8141, Fax. +61 2 9704 8139

Austria: Computerstr. 6, A-1101 WIEN, P.O. Box 213,
Tel. +43 1 60 101 1248, Fax. +43 1 60 101 1210

Belarus: Hotel Minsk Business Center, Bld. 3, r. 1211, Volodarski Str. 6,
220050 MINSK, Tel. +375 172 20 0733, Fax. +375 172 20 0773

Belgium: see The Netherlands

Brazil: see South America

Bulgaria: Philips Bulgaria Ltd., Energoproject, 15th floor,
51 James Bourchier Blvd., 1407 SOFIA,
Tel. +359 2 68 9211, Fax. +359 2 68 9102

Canada: PHILIPS SEMICONDUCTORS/COMPONENTS,
Tel. +1 800 234 7381, Fax. +1 800 943 0087

China/Hong Kong: 501 Hong Kong Industrial Technology Centre,
72 Tat Chee Avenue, Kowloon Tong, HONG KONG,
Tel. +852 2319 7888, Fax. +852 2319 7700

Colombia: see South America

Czech Republic: see Austria

Denmark: Sydhavnsgade 23, 1780 COPENHAGEN V,
Tel. +45 33 29 3333, Fax. +45 33 29 3905

Finland: Sinikalliontie 3, FIN-02630 ESPOO,
Tel. +358 9 615 800, Fax. +358 9 6158 0920

France: 51 Rue Carnot, BP317, 92156 SURESNES Cedex,
Tel. +33 1 4099 6161, Fax. +33 1 4099 6427

Germany: Hammerbrookstraße 69, D-20097 HAMBURG,
Tel. +49 40 2353 60, Fax. +49 40 2353 6300

Hungary: see Austria

India: Philips INDIA Ltd, Band Box Building, 2nd floor,
254-D, Dr. Annie Besant Road, Worli, MUMBAI 400 025,
Tel. +91 22 493 8541, Fax. +91 22 493 0966

Indonesia: PT Philips Development Corporation, Semiconductors Division,
Gedung Philips, Jl. Buncit Raya Kav.99-100, JAKARTA 12510,
Tel. +62 21 794 0040 ext. 2501, Fax. +62 21 794 0080

Ireland: Newstead, Clonskeagh, DUBLIN 14,
Tel. +353 1 7640 000, Fax. +353 1 7640 200

Israel: RAPAC Electronics, 7 Kehilat Saloniki St, PO Box 18053,
TEL AVIV 61180, Tel. +972 3 645 0444, Fax. +972 3 649 1007

Italy: PHILIPS SEMICONDUCTORS, Via Casati, 23 - 20052 MONZA (MI),
Tel. +39 039 203 6838, Fax +39 039 203 6800

Japan: Philips Bldg 13-37, Kohnan 2-chome, Minato-ku,
TOKYO 108-8507, Tel. +81 3 3740 5130, Fax. +81 3 3740 5057

Korea: Philips House, 260-199 Itaewon-dong, Yongsan-ku, SEOUL,
Tel. +82 2 709 1412, Fax. +82 2 709 1415

Malaysia: No. 76 Jalan Universiti, 46200 PETALING JAYA, SELANGOR,
Tel. +60 3 750 5214, Fax. +60 3 757 4880

Mexico: 5900 Gateway East, Suite 200, EL PASO, TEXAS 79905,
Tel. +9-5 800 234 7381, Fax +9-5 800 943 0087

Middle East: see Italy

Netherlands: Postbus 90050, 5600 PB EINDHOVEN, Bldg. VB,
Tel. +31 40 27 82785, Fax. +31 40 27 88399

New Zealand: 2 Wagener Place, C.P.O. Box 1041, AUCKLAND,
Tel. +64 9 849 4160, Fax. +64 9 849 7811

Norway: Box 1, Manglerud 0612, OSLO,
Tel. +47 22 74 8000, Fax. +47 22 74 8341

Pakistan: see Singapore

Philippines: Philips Semiconductors Philippines Inc.,
106 Valero St. Salcedo Village, P.O. Box 2108 MCC, MAKATI,
Metro MANILA, Tel. +63 2 816 6380, Fax. +63 2 817 3474

Poland: Al.Jerozolimskie 195 B, 02-222 WARSAW,
Tel. +48 22 5710 000, Fax. +48 22 5710 001

Portugal: see Spain

Romania: see Italy

Russia: Philips Russia, Ul. Usatcheva 35A, 119048 MOSCOW,
Tel. +7 095 755 6918, Fax. +7 095 755 6919

Singapore: Lorong 1, Toa Payoh, SINGAPORE 319762,
Tel. +65 350 2538, Fax. +65 251 6500

Slovakia: see Austria

Slovenia: see Italy

South Africa: S.A. PHILIPS Pty Ltd., 195-215 Main Road Martindale,
2092 JOHANNESBURG, P.O. Box 58088 Newville 2114,
Tel. +27 11 471 5401, Fax. +27 11 471 5398

South America: Al. Vicente Pinzon, 173, 6th floor,
04547-130 SÃO PAULO, SP, Brazil,
Tel. +55 11 821 2333, Fax. +55 11 821 2382

Spain: Balmes 22, 08007 BARCELONA,
Tel. +34 93 301 6312, Fax. +34 93 301 4107

Sweden: Kottbygatan 7, Akalla, S-16485 STOCKHOLM,
Tel. +46 8 5985 2000, Fax. +46 8 5985 2745

Switzerland: Allmendstrasse 140, CH-8027 ZÜRICH,
Tel. +41 1 488 2741 Fax. +41 1 488 3263

Taiwan: Philips Semiconductors, 6F, No. 96, Chien Kuo N. Rd., Sec. 1,
TAIPEI, Taiwan Tel. +886 2 2134 2886, Fax. +886 2 2134 2874

Thailand: PHILIPS ELECTRONICS (THAILAND) Ltd.,
209/2 Sanpavuth-Bangna Road Prakanong, BANGKOK 10260,
Tel. +66 2 745 4090, Fax. +66 2 398 0793

Turkey: Yukari Dudullu, Org. San. Blg., 2.Cad. Nr. 28 81260 Umraniye,
ISTANBUL, Tel. +90 216 522 1500, Fax. +90 216 522 1813

Ukraine: PHILIPS UKRAINE, 4 Patrice Lumumba str., Building B, Floor 7,
252042 KIEV, Tel. +380 44 264 2776, Fax. +380 44 268 0461

United Kingdom: Philips Semiconductors Ltd., 276 Bath Road, Hayes,
MIDDLESEX UB3 5BX, Tel. +44 208 730 5000, Fax. +44 208 754 8421

United States: 811 East Arques Avenue, SUNNYVALE, CA 94088-3409,
Tel. +1 800 234 7381, Fax. +1 800 943 0087

Uruguay: see South America

Vietnam: see Singapore

Yugoslavia: PHILIPS, Trg N. Pasica 5/v, 11000 BEOGRAD,
Tel. +381 11 3341 299, Fax.+381 11 3342 553

For all other countries apply to: Philips Semiconductors,
International Marketing & Sales Communications, Building BE-p, P.O. Box 218,
5600 MD EINDHOVEN, The Netherlands, Fax. +31 40 27 24825

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